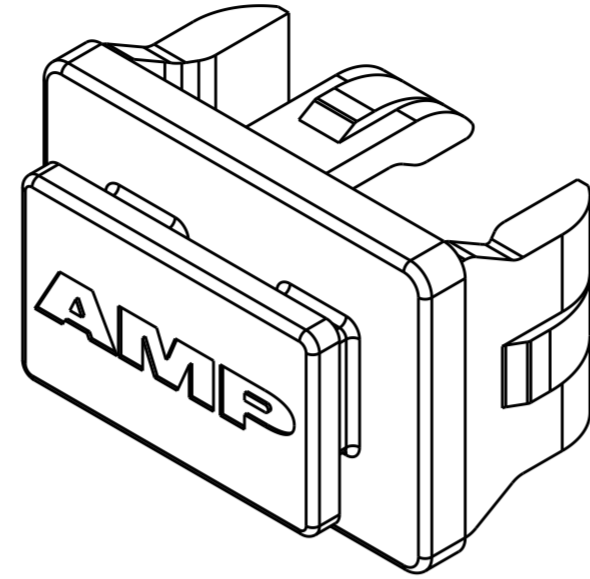
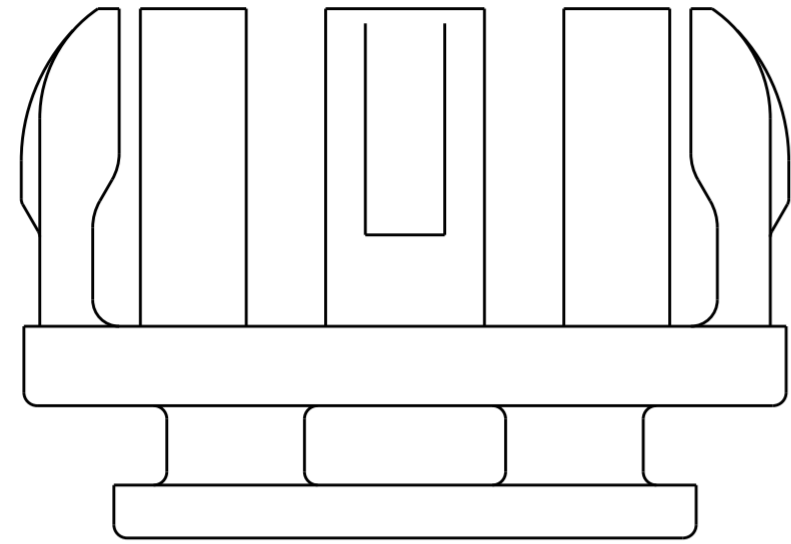


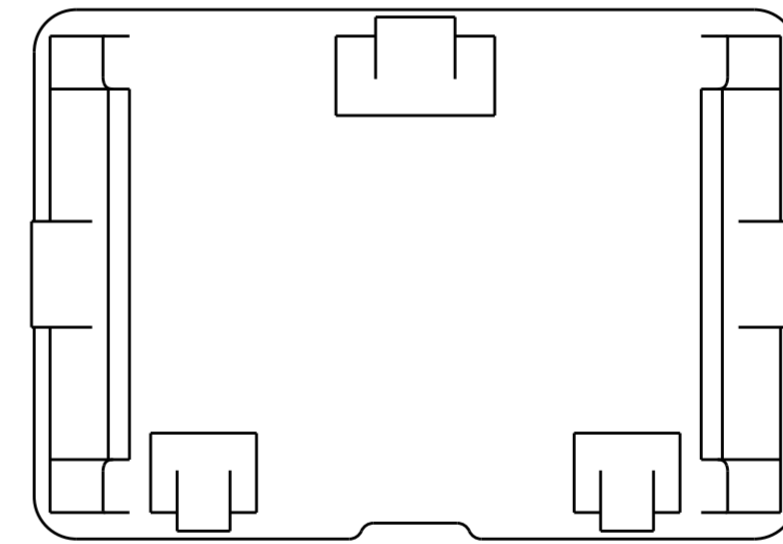
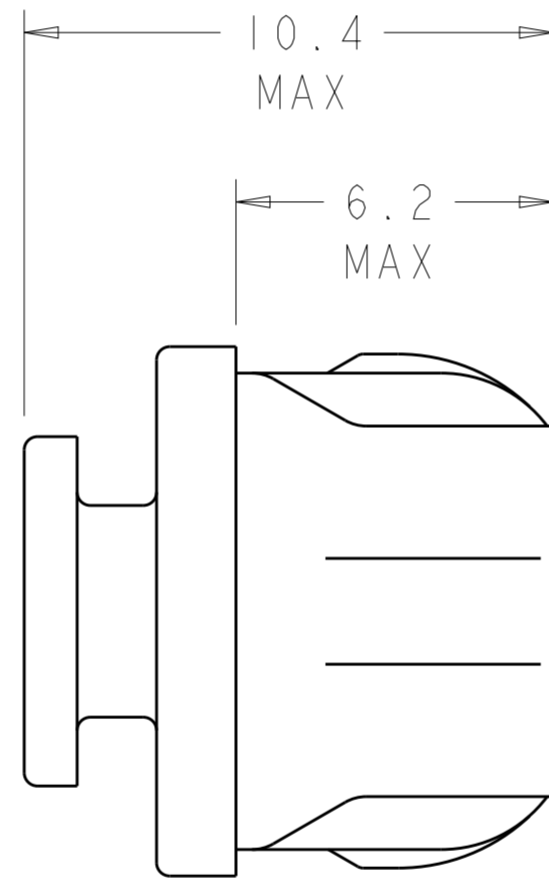
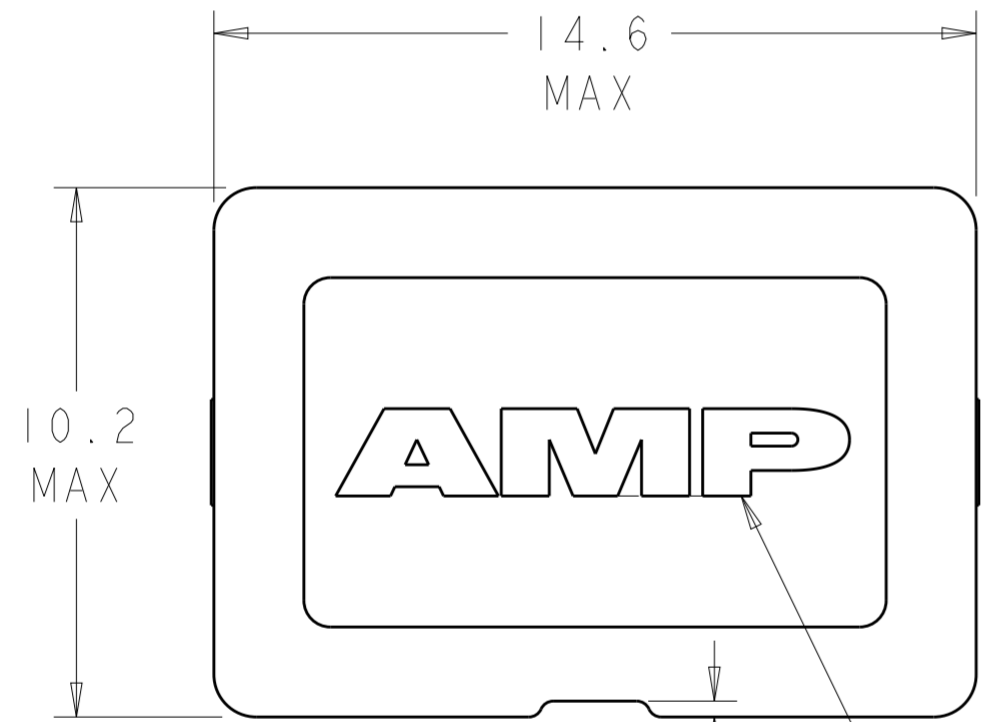
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LOC	DIST	REVISIONS					
GP	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
		C3		REVISED PER ECO-14-011961	5AUG2014	KS	MQ.W
		C4		REVISED PER ECO-15-007319	3JUN2015	JW	SH
		C5		REVISED PER ECO-15-011593	10AUG2015	JW	SH



SCALE 5:1

- ① THERMOPLASTIC MOLDING COMPOUND.
- ② TIN PLATING OVER COPPER PLATING.
- ③ OBSOLETE.



AMP LOGO FOR -1 & -2
 0.3 REF
 2.5 REF

NO	-	①	1367147-3
YES	②	1367147-1	③ 1367147-2
YES	-	①	1367147-1
AMP LOGO	FINISH	MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN P. KERLIN 30AUG2000	STE TE Connectivity	
DIMENSIONS: mm		CHK E. BRIGHT 30AUG2000		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD E. BRIGHT 30AUG2000	NAME COVER, SFP	
0 PLC ± 1 PLC ± 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ±		PRODUCT SPEC -	SIZE A200779	
MATERIAL SEE TABLE		APPLICATION SPEC -	DRAWING NO C-1367147	
FINISH SEE TABLE		WEIGHT -	RESTRICTED TO -	
CUSTOMER DRAWING		SCALE 7:1		SHEET 1 OF 1 REV C5

Mouser Electronics

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Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[1367147-3](#)